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Global Photoresists for Advanced IC Packaging Supply, Demand and Key Producers, 2023-2029

https://marketpublishers.com/r/G8C650390050EN.html
Date: July 2024
Pages: 118
Price: US$ 4,480.00 (Single User License)
ID: G8C650390050EN

Abstracts

The global Photoresists for Advanced IC Packaging market size is expected to reach $ 201 million by 2029, rising at a market growth of 5.5% CAGR during the forecast period (2023-2029).

In terms of product type, Thick Film Positive Photoresists accounting for 62% of the Photoresists for Advanced IC Packaging. And in terms of application, currently Thick Film Positive Photoresists are mainly used in semiconductor advanced packaging process, Wafer-Level Packaging and Flip Chip (FC) packaging, among them Flip Chip (FC) packaging is the largest application, with a share over 50%. Currently the Photoresists for Advanced IC Packaging are mainly produced in Japan, US, and Europe. Japan is the largest producer of thick layer photoresists, occupied over 55 percent, followed by Europe and North America. The global major manufacturers of Photoresists for Advanced IC Packaging include JSR, TOKYO OHKA KOGYO CO., LTD. (TOK), DuPont, and Merck KGaA (AZ), etc. In terms of revenue, the global 3 largest players have a market share over 80%.

This report studies the global Photoresists for Advanced IC Packaging production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Photoresists for Advanced IC Packaging, and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Photoresists for Advanced IC Packaging that contribute to its increasing demand across many markets.

Highlights and key features of the study

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Global Photoresists for Advanced IC Packaging total production and demand, 2018-2029, (K Units)

Global Photoresists for Advanced IC Packaging total production value, 2018-2029, (USD Million)

Global Photoresists for Advanced IC Packaging production by region & country, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Photoresists for Advanced IC Packaging consumption by region & country, CAGR, 2018-2029 & (K Units)

U.S. VS China: Photoresists for Advanced IC Packaging domestic production, consumption, key domestic manufacturers and share

Global Photoresists for Advanced IC Packaging production by manufacturer, production, price, value and market share 2018-2023, (USD Million) & (K Units)

Global Photoresists for Advanced IC Packaging production by Type, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Photoresists for Advanced IC Packaging production by Application production, value, CAGR, 2018-2029, (USD Million) & (K Units).

This reports profiles key players in the global Photoresists for Advanced IC Packaging market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include JSR, Tokyo Ohka Kogyo (TOK), Merck KGaA (AZ), DuPont, Shin-Etsu, Allresist, Futurrex, KemLab™ Inc and Youngchang Chemical, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Photoresists for Advanced IC Packaging market.

Detailed Segmentation:

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Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (K Units) and average price (US$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global Photoresists for Advanced IC Packaging Market, By Region:

- United States
- China
- Europe
- Japan
- South Korea
- ASEAN
- India
- Rest of World

Global Photoresists for Advanced IC Packaging Market, Segmentation by Type

- Thick Film Positive Photoresists
- Thick Film Negative Photoresists

Global Photoresists for Advanced IC Packaging Market, Segmentation by Application

- Wafer-Level Packaging
- 2.5D & 3D Packaging

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Others

Companies Profiled:

JSR

Tokyo Ohka Kogyo (TOK)

Merck KGaA (AZ)

DuPont

Shin-Etsu

Allresist

Futurrex

KemLab™ Inc

Youngchang Chemical

Everlight Chemical

Crystal Clear Electronic Material

Kempur Microelectronics Inc

Xuzhou B & C Chemical

nepes

Shanghai Sinyang Semiconductor Materials

eChem Slolutions Japan

Fuyang Sineva Material Technology

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Key Questions Answered

1. How big is the global Photoresists for Advanced IC Packaging market?

2. What is the demand of the global Photoresists for Advanced IC Packaging market?

3. What is the year over year growth of the global Photoresists for Advanced IC Packaging market?

4. What is the production and production value of the global Photoresists for Advanced IC Packaging market?

5. Who are the key producers in the global Photoresists for Advanced IC Packaging market?

6. What are the growth factors driving the market demand?

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